Declaration For U.S. Patent Application

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

In-Mold Foam Molding Apparatus and Method, and In-Mold Foam Molded Article

The specification of which is attached hereto unless the following is checked:

was filed on	as Un	ited States Application Number or PCI	' International	Application
Number	and was amen	nded on		
(if applicable).				
I hereby state that I have reviewed and any amendment referred to above.	understand the contents of the	e above-identified specification, including t	he claim(s), as	amended by
I acknowledge the duty to disclose inform	nation which is material to pa	tentability as defined in Title 37, Code of F	ederal Regulat	ions, § 1.56.
I hereby claim foreign priority benefits	s under Title 35. United Sta	ites Code, § 119 (a) - (d) of any foreign :	application(s) fo	or patent or
		foreign application for patent or inventor		
date before that of the application on wh	ich priority is claimed:			
			Priority Cla	aimed
H11(1999)-277440	Japan	29/09/99	— 🛚 Yes	🛄 No
(Number)	(Country)	(Day/Month/Year Filed)		_
H11(1999)-327512	Japan	17/11/99	🔯 Yes	□ No
(Number)	(Country)	(Day/Month/Year Filed)		
H11(1999)-327513	Japan	17/11/99	Yes	□ No
(Number)	(Country)	(Day/Month/Year Filed)		
H11(1999)-337091	Japan	29/11/99	🔯 Yes	\square_{N_0}
(Number)	(Country)	(Day/Month/Year Filed)		
☐ See	e attached list for additional pr	rior foreign applications.		
I hereby claim the benefit under Title 35	i, United States Code, § 119(e)	of any United States provisional applicati	on(s) listed belo	w.
(Application Number)		(Filing Date)		
(Ap	oplication Number)	(Filing Date)		

I hereby claim that the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application

(List Prior U.S. Applications)	(Application Serial Number)	(Filing Date)	(Status) (patented, pending, abandoned)
11.	(Application Serial Number)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

James E. Armstrong, III. Reg. No. 18,366; William F. Westerman, Reg. No. 29,988: Ken-Ichi Hattori, Reg. No. 32,861; Le-Nhung McLeland, Reg. No. 31,541; Ronald F.Naughton, Reg. No. 24,616; John R. Pegan. Reg. No.18,069; William G. Kratz, Jr., Reg. No. 22,631; Albert Tockman. Reg. No. 19,722; Mel R. Quintos, Reg. No. 31,898; Donald W. Hanson. Reg. No. 27,133; Stephen G. Adrian. Reg. No. 32,878; William L. Brooks. Reg. No. 34,129; John F. Carney. Reg. No. 20,276; Edward F. Welsh. Reg. No. 22,455; Patrick D. Muir. Reg. No. 37,403; Gay A. Spahn. Reg. No. 34,978; and John P. Kong, Reg. No. 40,054.

Please direct all communications to the following address:

ARMSTRONG, WESTERMAN, HATTORI, McLELAND & NAUGHTON 1725 K Street, N.W., Suite 1000 Washington, D.C. 20006

TEL.: (202) 659-2930 FAX: (202) 887-0357

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor (given name, family name)Masahiko_SAMES	HIMA	
Inventor's signature	Date	Sep. 5. 2000
Residence Settsu-shi, Osaka, Japan	Citizenship	JAPAN
Post Office Address5-5-31-104, Torikainishi, Settsu-shi, Osaka 566-0072 Japan		
Full name of sole or second inventor (given name, family name)Yoshiyuki KOBAYA	CIII	
Inventor's signature 1, 75 2	Date .	Sep. 5. 1000
	Citizenship	JAPAN
Ost Office Address 1-111-1, Fujii, Ohji-cho, Kitakatsuragi-gun, Nara 636-0014 Japan		
Full name of sole or third inventor (given name, family name) Kenji YAMAGUCH	Ш	
Inventor's signature	Date .	Jep. 5 2000
		JAPAN
Post Office Address 2-3, Wakayamadai, Shimamoto-cho, Mishima-gun, Osaka 618-00		
Full many of all and count in the district of the second o		
Full name of sole or fourth inventor (given name, family name)		
Inventor's signature	Date _	
Residence	Citizenship	
Post Office Address		
Full name of sole or fifth inventor (given name, family name)		
Inventor's signature	Date _	
Residence	Citizenship	
Post Office Address		
Full name of sole or sixth inventor (given name, family name)		
Inventor's signature	Date _	
Residence	4	
Post Office Address	Oniz nsinp	
100 01100 11111111111111111111111111111		
Full name of sole or seventh inventor (given name, family name)		
Inventor's signature	Date _	····
Residence	Citizenship	
Post Office Address		
Full name of sole or eighth inventor (given name, family name)		
Inventor's signature	Date	
Residence	Citizenship	
Post Office Address		